

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HONG ZHU	03/02/2011
JIANPING YANG	03/02/2011
RECEIVING PARTY DATA	
Name:	Semiconductor Manufacturing International (Shanghai) Corporation
Street Address:	18 Zhang Jiang Road, Pudong New Area
City:	Shanghai
State/Country:	CHINA
Postal Code:	201203
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12848229
CORRESPONDENCE DATA	
Fax Number:	(650)326-2422
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	415-576-0200
Email:	jsalvador@kilpatricktownsend.com
Correspondent Name:	KILPATRICK TOWNSEND AND STOCKTON LLP
Address Line 1:	Two Embarcadero Center, Eighth Floor
Address Line 4:	San Francisco, CALIFORNIA 94111-3834
ATTORNEY DOCKET NUMBER:	021653-019500US
NAME OF SUBMITTER:	Dah-Bin Kao
Total Attachments: 1 source=021653-019500US EXECUTED ASSIGNMENT#page1.tif	

CH \$40.00 12848229

Attorney Docket No.: 021653-019500US
 Client Reference No.: 2004-00299-SH-US

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, **Hong Zhu** of 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203; People's Republic of China and **Jianping Yang** of 18 Zhang Jiang Rd., Pudong New Area, Shanghai, 201203, People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: **METHOD AND SYSTEM FOR CMOS IMAGE SENSING DEVICE**

Date(s) of execution of Declaration:

Filing Date: **August 2, 2010**

Application No.: **12/848,229** ; and

WHEREAS, Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of People's Republic of China, located at 18 Zhang Jiang Rd, Pudong New Area, Shanghai, 201203, People's Republic of China, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

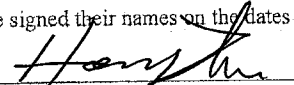
For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignor, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.


IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: 3/2/11



 Hong Zhu

Dated: 3/2/11



 Jianping Yang

62396070 v1